



L	Hits	Search Text	DB	Time stamp
Number				, -
1	5258	"inductive couple plasma" or ICP	USPAT;	2003/04/03
		-	EPO; JPO;	08:32
			IBM_TDB	
2	29		USPAT;	2003/04/03
		"boron thichloride" or "BCl.sub.3" or	EPO; JPO;	11:00
		chlorine or "Cl.sub.2") and volume and	IBM_TDB	1
	İ	pressure and "flow rate"		
3	50	(AlCu or "copper-aluminum") same (BCl3 or	USPAT;	2003/04/03
	ŀ	"boron thichloride" or "BCl.sub.3" or	EPO; JPO;	09:36
		chlorine or "Cl.sub.2") same etch\$3	IBM_TDB	
7	396	(gas adj time) and etch\$3	USPAT;	2003/04/03
			EPO; JPO;	09:41
			IBM_TDB	
8	14	("inductive couple plasma" or ICP) and	USPAT;	2003/04/03
		((gas adj time) and etch\$3)	EPO; JPO;	09:39
			IBM_TDB	0000/04/00
9	9178	etch\$3 and volume and pressure and "flow	USPAT;	2003/04/03
		rate"	EPO; JPO;	09:44
			IBM_TDB	2222/24/22
10	194	etch\$3 same volume same pressure same	USPAT;	2003/04/03
		"flow rate"	EPO; JPO;	10:32
	2.4	Waterbalan taken Wang da Antonia na ada ana lama	IBM_TDB USPAT;	2003/04/03
11	14		EPO; JPO;	10:33
		and pressure and "flow rate"	IBM TDB	10:33
12	58	(AlCu or "copper-aluminum") same (BCl3 or	USPAT;	2003/04/03
12	36	"boron thichloride" or "BCl.sub.3" or	EPO; JPO;	10:59
		chlorine or "Cl.sub.2")	IBM TDB	10.33
14	281	(AlCu or "copper-aluminum") and (BC13 or	USPAT;	2003/04/03
17	2.01	"boron thichloride" or "BCl.sub.3" or	EPO; JPO;	11:00
İ		chlorine or "Cl.sub.2")	IBM TDB	1
16	127	((AlCu or "copper-aluminum") and (BC13 or	USPAT;	2003/04/03
10	1	"boron thichloride" or "BCl.sub.3" or	EPO; JPO;	11:01
		chlorine or "Cl.sub.2")) and 438/\$.ccls.	IBM TDB	
17	2093		USPAT;	2003/04/03
		(438/720)).CCLS.	EPO; JPO;	11:01
			IBM TDB	
18	27		USPĀT;	2003/04/03
		"boron thichloride" or "BCl.sub.3" or	EPO; JPO;	11:01
		chlorine or "Cl.sub.2")) and (((438/706)	IBM_TDB	
		or (438/710) or (438/712) or		
		(438/720)).CCLS.)		